

LPDDR3 Part Number

H 9 **XXXXXX** **XXXXXX** **XXXXXX** - **XXX**

1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17

SK Hynix MEMORY

PRODUCT FAMILY

9 : MCP

PRODUCT MODE

CC : MCP DDR3 Only
 CK : PoP DDR3 Only

NVM Density, Stack

NN : None

NVM Voltage, I/O

N : None

DRAM Density, Stack, Ch, CS

4G : 4Gb, SDP
 8G : 8Gb, SDP
 8J : 8Gb, DDP, 1Ch, 2CS
 8K : 8Gb, DDP, 2Ch, 1CS
 BJ : 16Gb, DDP, 1Ch, 2CS
 BK : 16Gb, DDP, 2Ch, 1CS
 BL : 16Gb, QDP, 1Ch, 2CS
 BP : 16Gb, QDP, 2Ch, 2CS
 DA : 24Gb, QDP, 2Ch, 2CS

DRAM Voltage, I/O

T : 1.2V/1.2, x32

OPERATING TEMPERATURE

M : Mobile (-30°C~85°C)
 H : Mobile Extended (-30°C~105°C)

DRAM SPEED

K : DDR3 1333 (CL10)
 T : DDR3 1600 (CL12)
 U : DDR3 1866 (CL14)

NVM Speed

N : None

PACKAGE MATERIAL

R : Lead & Halogen free
 (ROHS¹) Compliant)

PACKAGE TYPE

LA : FBGA 178Ball
 LB : FBGA 253Ball
 PL : FBGA 168Ball
 RP : FBGA 256Ball
 TD : FBGA 216Ball 0.27ball(BDP)

DIE GENERATION

M : 1st
 A : 2nd
 B : 3rd
 C : 4th
 D : 5th

Note:

1) ROHS : Restriction Of Hazardous Substances